

Title (en)

PROCESS FOR MANUFACTURING ELECTRONIC-COMPONENT PACKAGES AND ELECTRONIC-COMPONENT PACKAGE OBTAINED BY MEANS OF THIS PROCESS

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRONIKKOMPONENTENGEHÄUSEN UND DURCH DIESES VERFAHREN HERGESTELLTES ELEKTRONIKKOMPONENTENGEHÄUSE

Title (fr)

PROCÉDÉ DE FABRICATION DE BOÎTIERS DE COMPOSANT ÉLECTRONIQUE ET BOÎTIER DE COMPOSANT ÉLECTRONIQUE OBTENU PAR CE PROCÉDÉ

Publication

EP 3821458 A1 20210519 (FR)

Application

EP 19749397 A 20190710

Priority

- FR 1856526 A 20180713
- FR 2019051729 W 20190710

Abstract (en)

[origin: WO2020012120A1] The invention relates to a process for manufacturing integrated-circuit packages (110), wherein a cavity is made in a strip of dielectric material covered with a leaf of electrically conductive material. An electronic component (90) is placed in the cavity and it is encapsulated by filling the cavity at least partially with an encapsulation material (100). The bottom of the blind cavity being formed of a layer of flexible and removable material which is removed after encapsulation. The invention also relates to integrated-circuit packages (110) manufactured according to this process. These integrated-circuit packages (110) are for example QFN packages.

IPC 8 full level

H01L 21/56 (2006.01); **H01L 21/48** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP)

H01L 21/4821 (2013.01); **H01L 21/568** (2013.01); **H01L 21/6835** (2013.01); **H01L 23/49537** (2013.01); **H01L 23/49541** (2013.01); **H01L 21/561** (2013.01); **H01L 24/48** (2013.01); **H01L 24/85** (2013.01); **H01L 2224/16245** (2013.01); **H01L 2224/48091** (2013.01); **H01L 2224/48177** (2013.01); **H01L 2224/48247** (2013.01); **H01L 2224/81005** (2013.01); **H01L 2224/85005** (2013.01); **H01L 2224/97** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/18165** (2013.01)

Citation (search report)

See references of WO 2020012120A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2020012120 A1 20200116; CN 112470261 A 20210309; EP 3821458 A1 20210519; FR 3083920 A1 20200117; SG 11202100314P A 20210225

DOCDB simple family (application)

FR 2019051729 W 20190710; CN 201980046879 A 20190710; EP 19749397 A 20190710; FR 1856526 A 20180713; SG 11202100314P A 20190710